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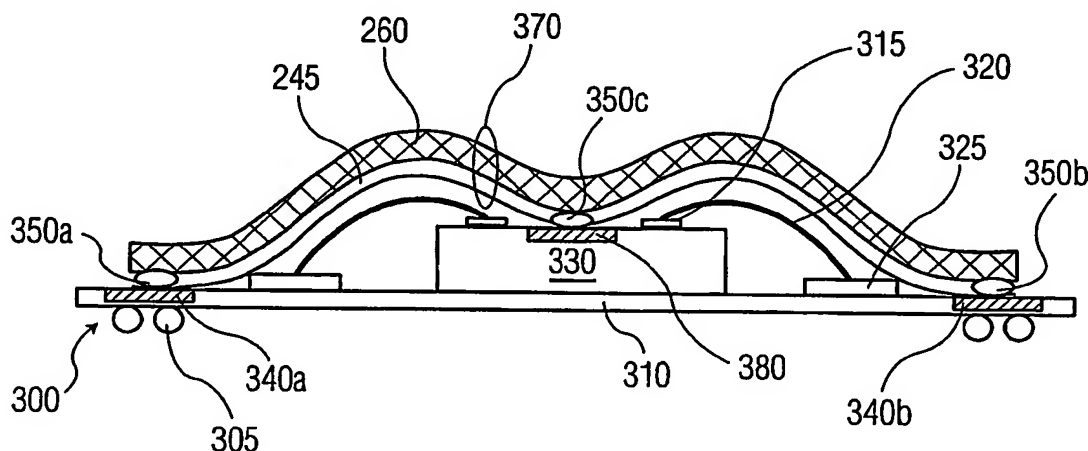
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— as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for the following designations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA,

[Continued on next page]

(54) Title: GROUND ARCH FOR WIREBOND BALL GRID ARRAYS



(57) Abstract: A structure provides for the control of bond wire impedance. In an example embodiment, there is an integrated circuit device (100) comprising an integrated circuit (130) having a plurality (115) of grounding pads, signal pads, and power pads and a package (110) for mounting the integrated circuit and includes a conductive path having at least one reference trace (140) that surrounds the integrated circuit. A grounding arch (170) formed by a dielectric-coated metal tape is disposed over the integrated circuit and connected to its ground pad in order to provide heat dissipation and EMI shielding.

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- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

- with international search report
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